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PMP9755

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
C1, C6	2	150uF	CAP, TA, 150uF, 6.3V, +/-20%, 0.07 ohm, SMD	3528-21	T520B157M006ATE070	Kemet		
C2	1	2.2uF	CAP, CERM, 2.2uF, 10V, +/-10%, X5R, 0603	0603	GRM188R61A225KE34D	MuRata		
C3	1	100000000uF	CAP, Electric Double Layer, 100 F, 2.7 V, +30/-50%, 0.03 ohm, TH	25x50mm	HVZ0E107NF-LT	Kemet		
C4	1	2.2uF	CAP, CERM, 2.2uF, 6.3V, +/-10%, X5R, 0603	0603	GRM188R60J225KE19D	MuRata		
C8	1	4700uF	CAP, AL, 4700uF, 6.3V, +/-20%, 0.015 ohm, TH	12.5x25mm	EEUFR0J472	Panasonic		
C9	1	4.7uF	CAP, CERM, 4.7 uF, 16 V, +/- 10%, X5R, 0603	0603	GRM188R61C475KAAJ	MuRata		
C10	1	10uF	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	0603	GRM188R61A106ME69	MuRata		
C11	1	1uF	CAP, CERM, 1uF, 6.3V, +/-10%, X5R, 0603	0603	GRM185R60J105KE26D	MuRata		
D1	1	30V	Diode, Schottky, 30V, 1.5A, DO-220AA	DO-220AA	SS1P3L-M3/84A	Vishay-Semiconductor		
D2	1	20V	Diode, Schottky, 20V, 0.5A, SOD-123	SOD-123	MBR0520L11G	ON Semiconductor		
J1, J2	2		Header, TH, 100mil, 6x1, Gold plated, 230 mil above insulator	TSW-106-07-G-S	TSW-106-07-G-S	Samtec, Inc.	Equivalent	Any
J3, J4	2		Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	TSW-103-07-G-S	TSW-103-07-G-S	Samtec, Inc.	Equivalent	Any
J5	1		CONN HEADER 1POS .100" SNGL TIN, TH	2.54mm Header	TSW-101-17-T-S	Samtec		
L1	1	6.1uH	Inductor, Shielded Drum Core, Ferrite, 6.1uH, 6.6A, 0.0176 ohm, SMD	CDRH127	CDRH127NP-6R1NC	Sumida		
Q1	1	20V	MOSFET, N/P-CH, 20V, 0.63A, SOT-416	SOT-416	SI1012CR-T1-GE3-ND	Vishay-Siliconix		None
R1	1	1.0k	RES, 1.0k ohm, 5%, 0.1W, 0603	0603	CRCW06031K00JNEA	Vishay-Dale		
R2	1	5.97k	RES, 5.97k ohm, 0.1%, 0.1W, 0603	0603	RT0603BRD075K97L	Yageo America		
R3, R11	2	49.9	RES, 49.9 ohm, 1%, 1W, 2512	2512	CRCW251249R9FKEG	Vishay-Dale		
R4, R8	2	100K	RES, 100k ohm, 0.5%, 0.1W, 0603	0603	RT0603DRE07100KL	Yageo America		
R6, R9	2	1.00Meg	RES, 1.00Meg ohm, 1%, 0.1W, 0603	0603	RC0603FR-071ML	Yageo America		
R7	1	909k	RES, 909k ohm, 1%, 0.1W, 0603	0603	RC0603FR-07909KL	Yageo America		
R10	1	124k	RES, 124k ohm, 1%, 0.1W, 0603	0603	CRCW0603124KFKEA	Vishay-Dale		
U1	1		Adjustable Precision Shunt Regulator, 34 ppm / degC, 100 mA, -40 to 85 degC, 3-pin SOT-23 (DBZ), Green (RoHS & no Sb/Br)	DBZ0003A	TL431AIDBZR	Texas Instruments	Equivalent	None
U2	1	TPS61030PWP	IC, Li ION, Boost converter, Adj V.	PWP16	TPS61030PWP	Texas Instruments		None
C5	0	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H101JA01D	MuRata		
C7	0	4700uF	CAP, AL, 4700uF, 6.3V, +/-20%, 0.015 ohm, TH	12.5x25mm	EEUFR0J472	Panasonic		
R5	0	100	RES, 100 ohm, 5%, 0.1W, 0603	0603	CRCW0603100RJNEA	Vishay-Dale		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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